BU508DF

GENERAL DESCRIPTION

High voltage, high-speed switching npn transistors in a fully isolated SOT199 envelope with integrated efficiency diode, primarily for use in horizontal deflection circuits of colour television receivers.

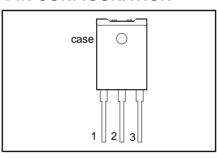
QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V_{CESM}	Collector-emitter voltage peak value	$V_{BF} = 0 \text{ V}$	-	1500	V
V _{CEO}	Collector-emitter voltage (open base)		-	700	V
	Collector current (DC)		-	8	Α
I _{CM}	Collector current peak value		-	15	Α
P _{tot}	Total power dissipation	$ T_{hs} \le 25 ^{\circ}C$ $ I_{C} = 4.5 A; I_{B} = 1.6 A$	-	34	W
V _{CEsat}	Collector-emitter saturation voltage	$I_{\rm C} = 4.5 \text{ A}; I_{\rm B} = 1.6 \text{ A}$	-	1.0	V
Csat	Collector saturation current	f = 16kHz	4.5	-	Α
V _F	Diode forward voltage	$I_{\rm F} = 4.5 {\rm A}$	1.6	2.0	V
t _f	Fall time	$I'_{Csat} = 4.5 \text{ A}; f = 16 \text{kHz}$	0.7	-	μs

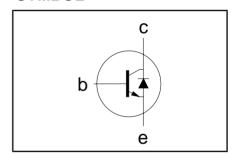
PINNING - SOT199

PIN	DESCRIPTION	
1	base	
2	collector	
3	emitter	
case	isolated	

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum Rating System (IEC 134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CESM}	Collector-emitter voltage peak value	$V_{RF} = 0 \text{ V}$	-	1500	V
V _{CEO}	Collector-emitter voltage (open base)		-	700	V
I _C	Collector current (DC)		-	8	Α
I _{CM}	Collector current peak value		-	15	Α
I _B	Base current (DC)		-	4	Α
I _{BM}	Base current peak value		-	6	Α
P _{tot}	Total power dissipation	T _{hs} ≤ 25 °C	-	34	W
T _{stg}	Storage temperature		-65	150	°C
T_j	Junction temperature		-	150	°C

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
R _{th j-hs}	Junction to heatsink	without heatsink compound	-	3.7	K/W
R _{th j-hs}	Junction to heatsink	with heatsink compound	-	2.8	K/W
R _{th j-a}	Junction to ambient	in free air	35	-	K/W

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ISOLATION LIMITING VALUE & CHARACTERISTIC

 T_{hs} = 25 °C unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{isol}	Repetitive peak voltage from all three terminals to external heatsink	R.H. ≤ 65 % ; clean and dustfree	-		2500	V
C _{isol}	Capacitance from T2 to external heatsink	f = 1 MHz	-	22	-	pF

STATIC CHARACTERISTICS

T_{hs} = 25 °C unless otherwise specified

113	10					
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CES}	Collector cut-off current 1	$V_{BE} = 0 \text{ V}; V_{CE} = V_{CESMmax}$	-	-	1.0	mΑ
I _{CES}			-	-	2.0	mA
V _{CEOsust}	Collector-emitter sustaining voltage	I _j = 125 °C I _B = 0 A; I _C = 100 mA; L = 25 mH	700	-	-	V
V_{CEsat}	Collector-emitter saturation voltages	$I_0 = 4.5 \text{ A}$: $I_0 = 1.6 \text{ A}$	-	-	1.0	V
V _{BEsat}	Base-emitter saturation voltage	$I_{\rm C} = 4.5 \text{ A}; I_{\rm B} = 2.0 \text{ A}$	-	-	1.1	V
h _{FE} V _F	DC current gain	$I_{\rm C} = 100 {\rm mA}; {\rm V}_{\rm CE} = 5 {\rm V}$	6	13	30	
V_{F}	Diode forward voltage	$I_{\rm F} = 4.5 {\rm A}$	-	1.6	2.0	V

DYNAMIC CHARACTERISTICS

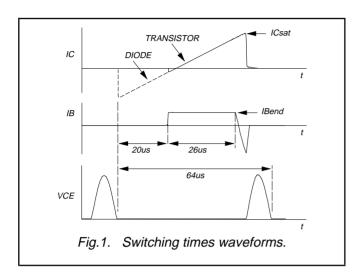
T_{hs} = 25 °C unless otherwise specified

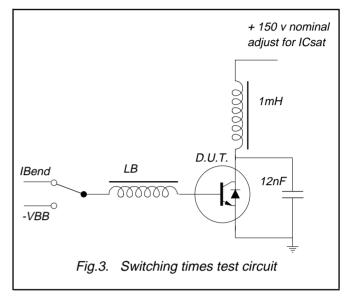
SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
f_T	Transition frequency at f = 5 MHz	$I_{C} = 0.1 \text{ A; } V_{CE} = 5 \text{ V}$	7	ı	MHz
C _c	Collector capacitance at f = 1MHz	V _{CB} = 10 V	125	ı	pF
t _s	Switching times (16 kHz line deflection circuit) Turn-off storage time Turn-off fall time	$ \begin{vmatrix} I_{Csat} = 4.5 \text{ A;} L_c \text{ 1 mH;} C_{fb} = 4 \text{ nF} \\ I_{B(end)} = 1.4 \text{ A;} L_B = 6 \mu\text{H;} \text{ -V}_{BB} = \text{-4 V;} \\ -I_{BM} = 2.25 \text{ A} \end{vmatrix} $	6.5 0.7	1 1	μs μs

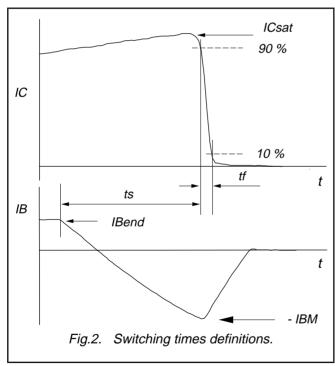
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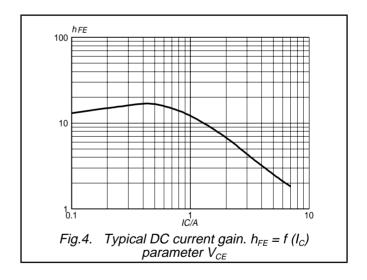
¹ Measured with half sine-wave voltage (curve tracer).

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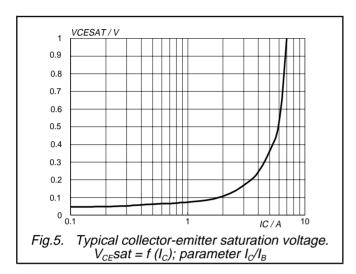


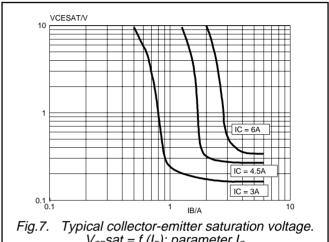




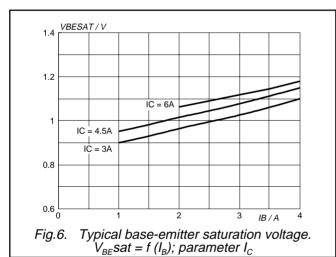


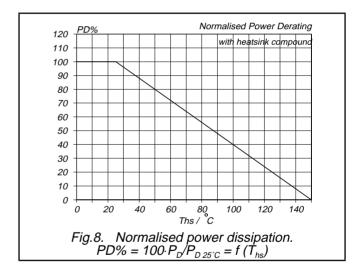
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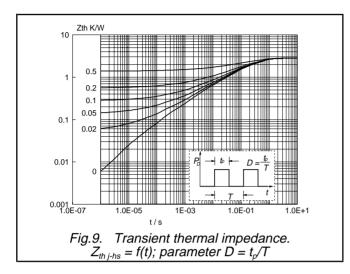


Typical collector-emitter saturation voltage. V_{CE} sat = $f(I_B)$; parameter I_C





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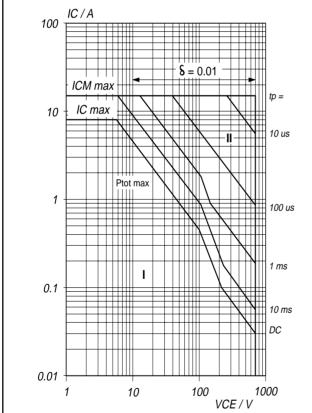


Fig.10. Forward bias safe operating area. $T_{hs} = 25^{\circ}C$ l Region of permissible DC operation. Il Extension for repetitive pulse operation.

NB: Mounted with heatsink compound and 30 ± 5 newton force on the centre of the envelope.

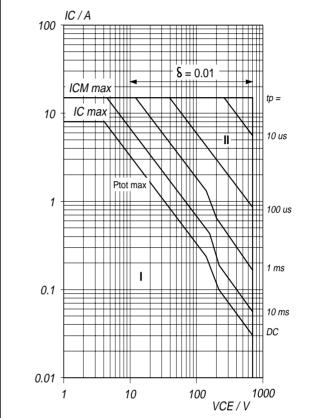
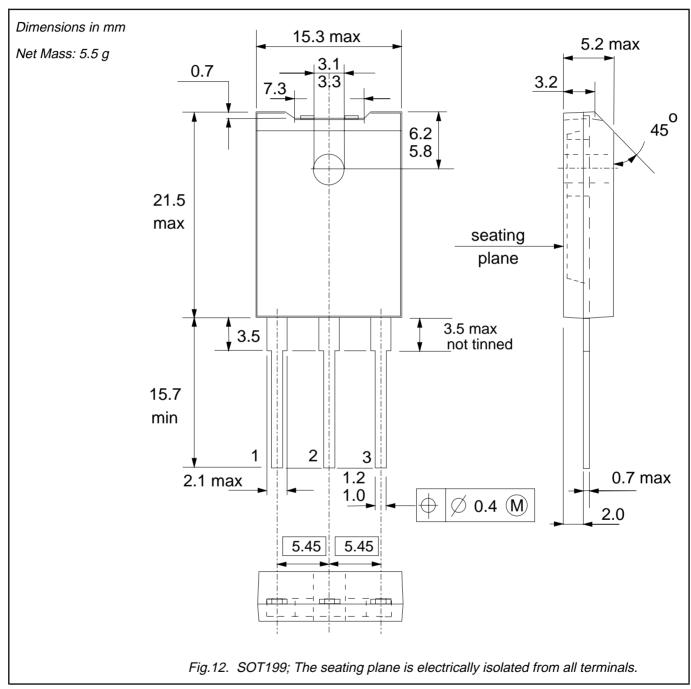


Fig.11. Forward bias safe operating area. $T_{hs} = 25\,^{\circ}\text{C}$ l Region of permissible DC operation. Il Extension for repetitive pulse operation.

NB: Mounted without heatsink compound and 30 ± 5 newton force on the centre of the envelope.

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MECHANICAL DATA



- Notes
 1. Refer to mounting instructions for F-pack envelopes.
 2. Epoxy meets UL94 V0 at 1/8".

Philips Semiconductors Product specification

Silicon Diffused Power Transistor

BU508DF

DEFINITIONS

Data sheet status				
Objective specification	This data sheet contains target or goal specifications for product development.			
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.			
Product specification	This data sheet contains final product specifications.			
Limiting values				

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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